

Section

MV Semi-conductor

Application

Field

Production

**PRODUCT BENEFITS**

4 adjustable scoring depth
Easy catch of the semicon
Light

TOOL CAPACITY

Diameter	10 - 100 mm 0,394 - 3,937 inch
Scoring depth	0.4 / 0.6 / 0.9 / 1.1 mm 0.016 / 0.024 / 0.035 / 0.043 inch
Min remaining length	10 mm / jacket - 4mm / screen

TOOL DIMENSIONS

Length	135 mm
Width	55 mm
Height	35 mm
Weight without box	0,16 Kg
Packaging	Box

ALROC SAS

Z.I. de la Fonderie - 72160 TUFFE
FRANCE

Phone: +33 2 43 71 11 80

Fax number : +33 2 43 71 16 51

www.alroc.fr

Tool to perform controlled longitudinal scoring on peelable semiconductor

TO DO WHAT

The ORACL enables the user to score longitudinally the peelable semiconductive layer in order to peel it off by hand.

Adjustable scoring depths (0.4 / 0.6 / 0.9 / 1.1 mm)

**Spare part**

LSO - Spare blade for peelable semiconductor

Associated tool

DSP - Peelable semiconductor lifter

MVS - Stop for tools

MV cables Tools
ORACL



Part Number	Diameter	Tool capacity		Dimensions			Packaging
		Scoring depth	Min remaining length	Length	Width	Height	
ORACL	10 - 100 mm 0,394 - 3,937 in	0.4 / 0.6 / 0.9 / 1.1 mm 0.016 / 0.024 / 0.035 / 0.043 inch	10 mm / jacket - 4mm / screen	135 mm 5,315 in	55 mm 2,165 in	35 mm 1,378 in	box